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PREPARATION OF PLYWOOD

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PUBLISHED: March 01, 1983 (19830301)
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ABSTRACT

PURPOSE: To prepare plywoods which emits a reduced amount of formaldehyde, by using an aged urea resin adhesive solution containing free urea to which defatted soya bean powder has been added.

CONSTITUTION: A mixed adhesive solution prepared by mixing wheat flour, water, hardener and defatted soya bean powder into a urea resin adhesive commonly used for plywood consisting of a low-formaldehyde urea resin which contains free urea or containing urea in an amount equal to that of free urea, is aged as it is for five hours or longer. The defatted soya bean powder is added in about 3-30pts.wt. per 100pts.wt. resin. A plywood made by coating the aged adhesive, followed by cold pressing and curing by hot pressing, shows a marked decrease of formaldehyde as compared with those coated with a conventional unaged adhesive solution and heat cured.

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PREPARATION OF PLYWOOD (English)

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GOHANNOSEIZOHOO (English)

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